



Description

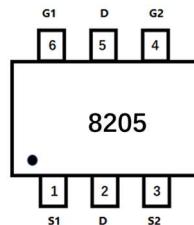
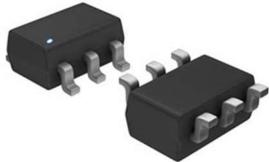
JMT Dual N-channel Enhancement Mode Power MOSFET

Features

- 20V, 5A
- $R_{DS(ON)} < 26m\Omega$ @ $V_{GS} = 4.5V$
- $R_{DS(ON)} < 34m\Omega$ @ $V_{GS} = 2.5V$
- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

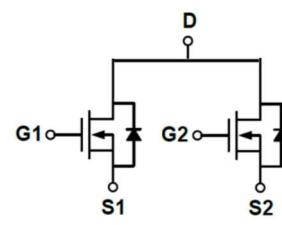
Application

- Load Switch
- PWM Application
- Power management



SOT23-6L(Dual)

Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
8205	JMTM8205A	TAPING	SOT23-6L	7inch	3000	180000

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	5	A
		$T_A = 100^\circ C$	3.2	A
I_{DM}	Pulsed Drain Current ^{note1}		20	A
P_D	Power Dissipation	$T_A = 25^\circ C$	1.5	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		83.3	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	0.5	0.66	1.2	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS}=4.5\text{V}$, $I_D=5\text{A}$	-	18	26	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$, $I_D=3\text{A}$	-	23	34	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	800	-	pF
C_{oss}	Output Capacitance		-	155	-	pF
C_{rss}	Reverse Transfer Capacitance		-	125	-	pF
Q_g	Total Gate Charge	$V_{DS}=10\text{V}$, $I_D=3\text{A}$, $V_{GS}=4.5\text{V}$	-	11	-	nC
Q_{gs}	Gate-Source Charge		-	2.3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	2.5	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=10\text{V}$, $I_D=3\text{A}$, $R_{\text{GEN}}=3\Omega$, $V_{GS}=4.5\text{V}$	-	18	-	ns
t_r	Turn-on Rise Time		-	5	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	43	-	ns
t_f	Turn-off Fall Time		-	20	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	6.5	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	26	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=5\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

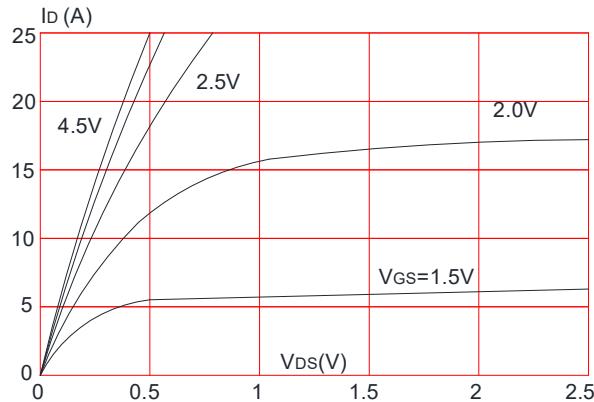


Figure 2: Typical Transfer Characteristics

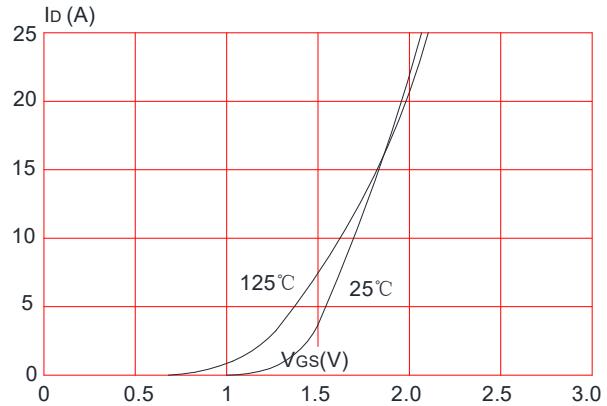


Figure 3: On-resistance vs. Drain Current

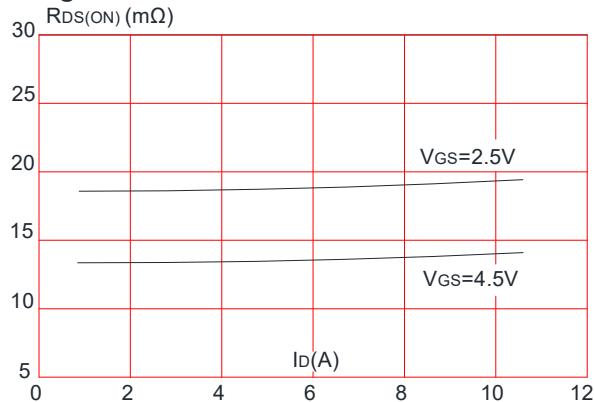


Figure 4: Body Diode Characteristics

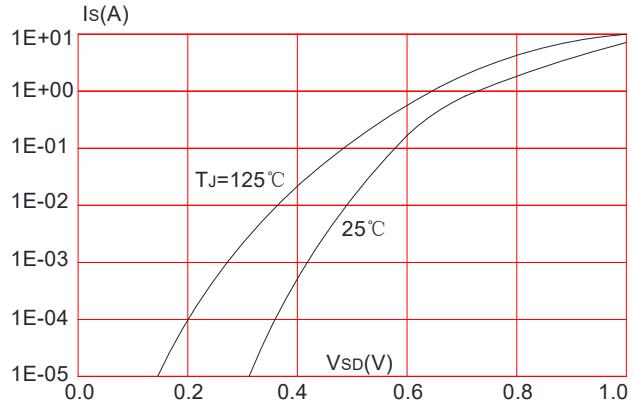


Figure 5: Gate Charge Characteristics

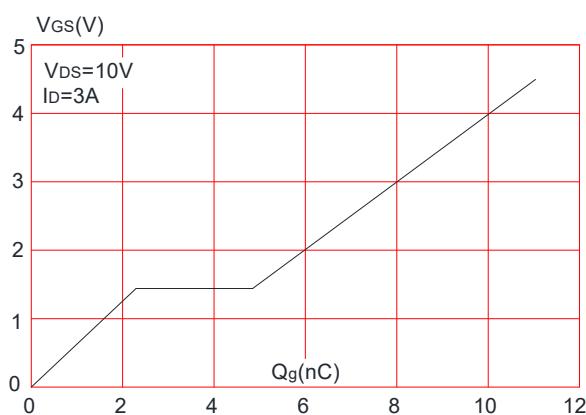


Figure 6: Capacitance Characteristics

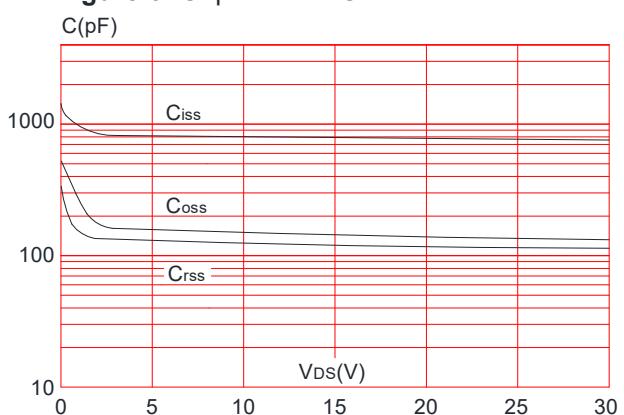


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

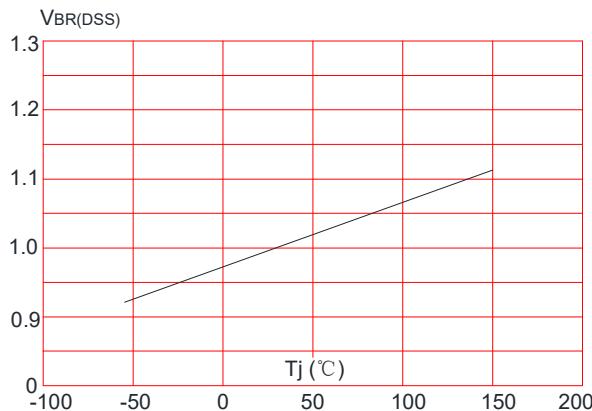


Figure 8: Normalized on Resistance vs. Junction Temperature

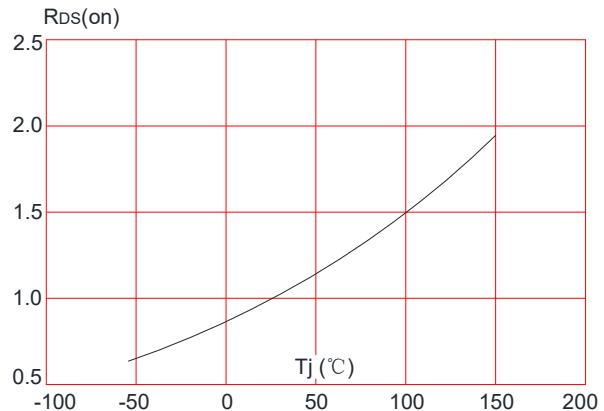


Figure 9: Maximum Safe Operating Area

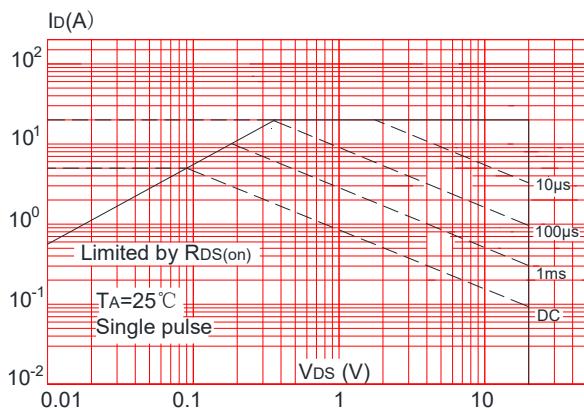


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

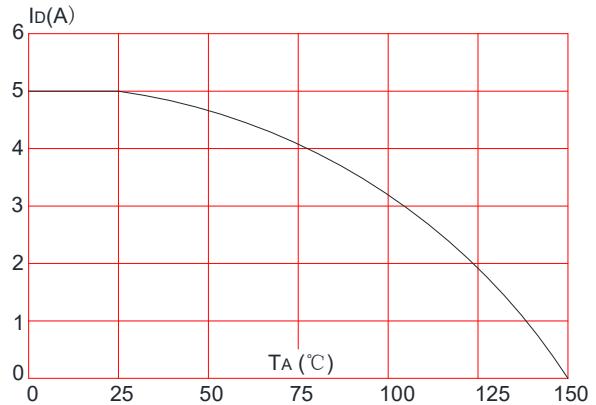
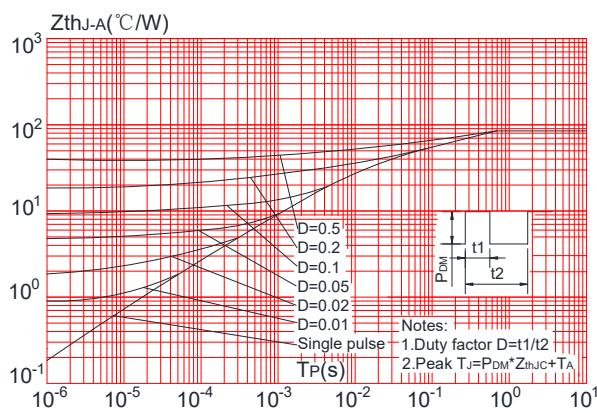


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Test Circuit

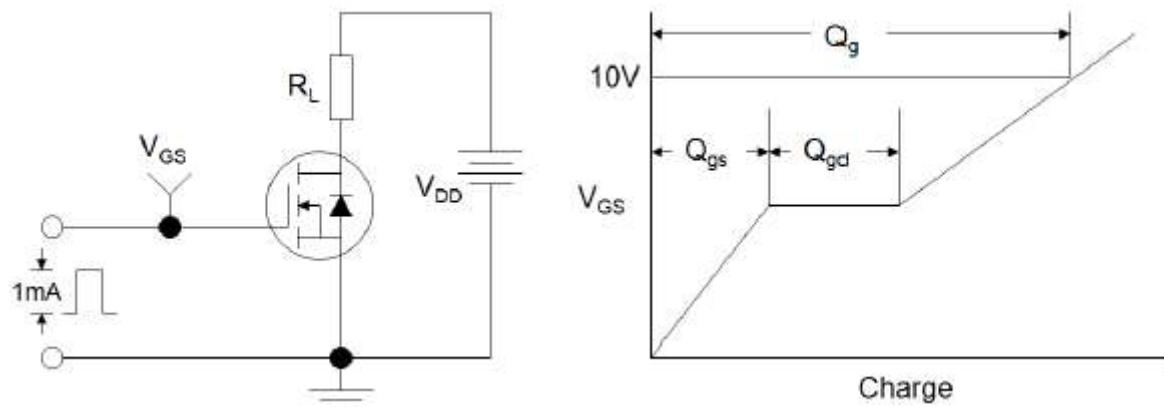


Figure1:Gate Charge Test Circuit & Waveform

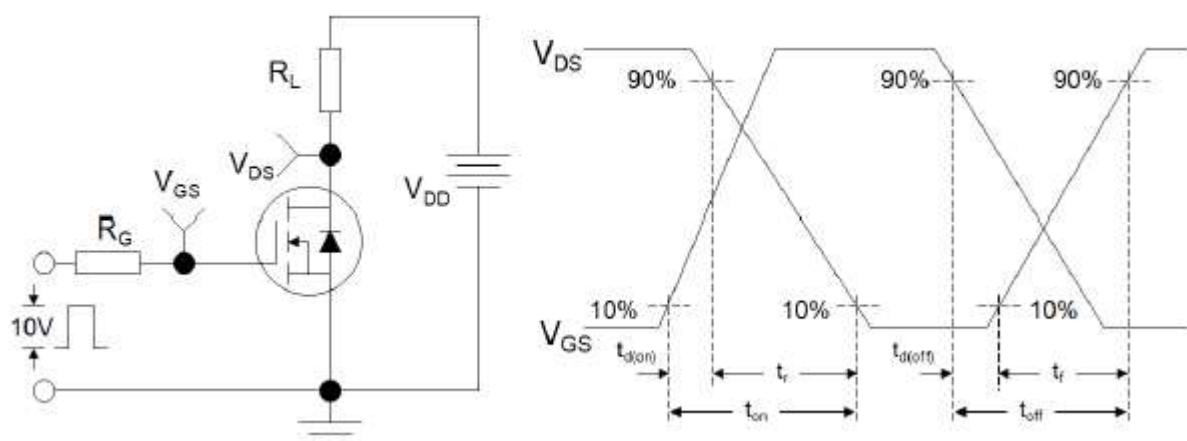


Figure 2: Resistive Switching Test Circuit & Waveforms

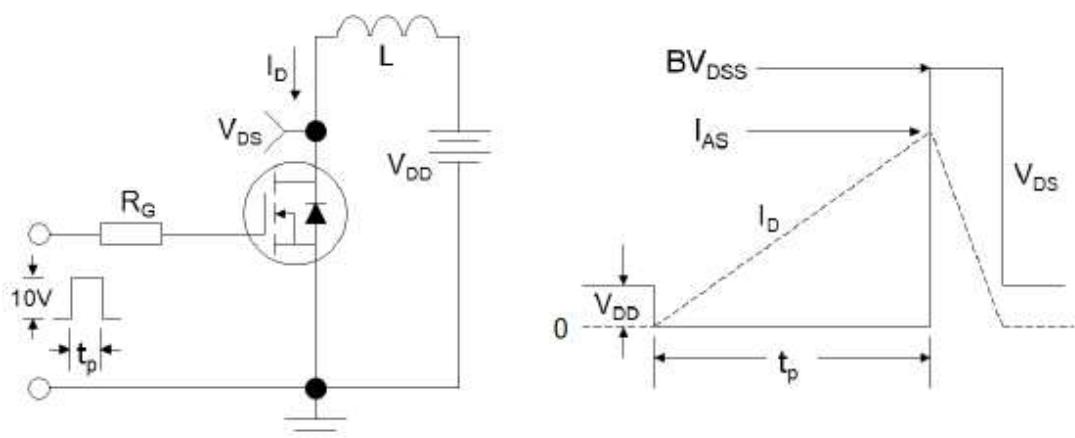
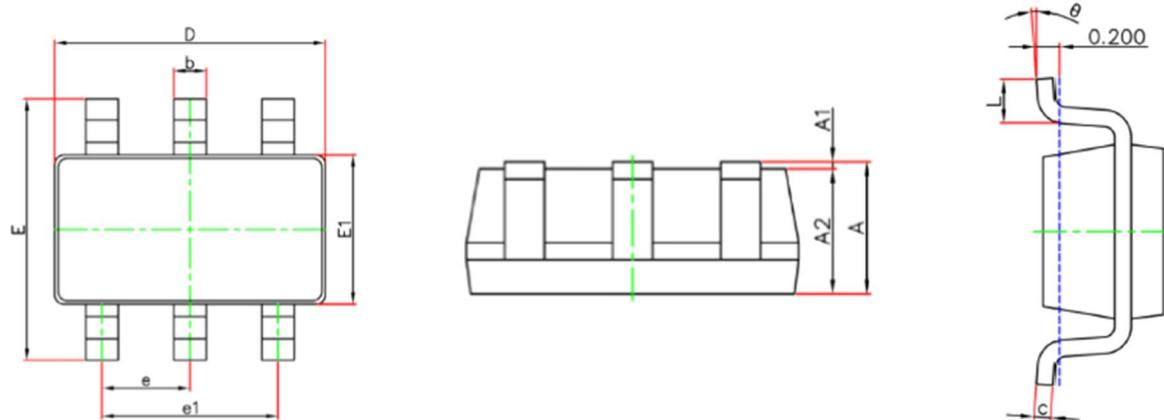


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data-SOT23-6L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950 (BSC)		0.037 (BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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